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NEXCHIP SEMICONDUCTOR CORPORATION

合肥晶合集成電路股份有限公司

(A joint stock company incorporated in the People's Republic of China with limited liability)

(Stock Code: 2249)

AMENDMENTS TO THE ARTICLES OF ASSOCIATION

This announcement is made by Nexchip Semiconductor Corporation (the “**Company**”) pursuant to Rule 13.51(1) of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited.

Reference is made to the prospectus of the Company dated June 30, 2026 in relation to the 2023 Restricted Stock Incentive Plan approved by the Shareholders of the Company on August 31, 2023 (the “**Incentive Plan**”). Unless the context otherwise requires, capitalized terms used herein shall have the same meanings as those defined in the prospectus.

On August 24, 2026, the Company announced that, as the vesting conditions for the first vesting period of the reserved portion for grant under the Incentive Plan have been satisfied, a total of 141,613 restricted Shares are available for vesting. For details, please refer to the overseas regulatory announcement published by the Company on August 24, 2026.

According to the Certificate of Securities Change Registration (《證券變更登記證明》) issued by China Securities Depository and Clearing Co., Ltd. Shanghai Branch, the Company has completed the registration for the above 141,613 additional A Shares (the “**Vesting**”). The additional A Shares were listed and circulated on September 18, 2026.

Immediately after the completion of the Vesting, the registered capital of the Company increased from RMB2,234,645,597 to RMB2,234,787,210, and the total number of Shares of the Company increased from 2,234,645,597 Shares to 2,234,787,210 Shares, of which ordinary A Shares increased from 2,007,591,697 Shares to 2,007,733,310 Shares, while ordinary H Shares remained unchanged at 227,053,900 Shares. To reflect the foregoing changes in the registered capital and capital structure of the Company, the Company has made corresponding amendments to the articles of association of the Company (the “**Articles of Association**”).

Details of the amendments to the Articles of Association are as follows:

Original articles	Amended articles
Article 6 The Company's registered capital is RMB2,234,645,597, and the total number of Shares is 2,234,645,597, all of which are ordinary Shares.	Article 6 The Company's registered capital is RMB2,234,787,210, and the total number of Shares is 2,234,787,210, all of which are ordinary Shares.
Article 20 All Shares of the Company are ordinary Shares with par value of RMB1 each, including 2,007,591,697 ordinary A Shares and 227,053,900 ordinary H Shares.....	Article 20 All Shares of the Company are ordinary Shares with par value of RMB1 each, including 2,007,733,310 ordinary A Shares and 227,053,900 ordinary H Shares.....

Pursuant to the relevant resolutions approved at the 2023 Second Extraordinary General Meeting of the Company, the general meeting of the Company has granted the Board the authorization to deal with matters relating to the Incentive Plan, including the amendments to the Articles of Association based on the implementation results of the Incentive Plan, the registration of registered capital change of the Company and other relevant matters. The above amendments shall take effect upon consideration and approval by the Board on September 29, 2026 without consideration by the general meeting.

The full text of the amended Articles of Association will be published on the website of the Stock Exchange (www.hkexnews.hk) and the website of the Shanghai Stock Exchange (www.sse.com.cn). The Company will complete the industrial and commercial registration, filing and other relevant procedures for the aforesaid amendments to the Articles of Association with the relevant government and regulatory authorities of the People's Republic of China in accordance with applicable laws and regulations. The final version of the Articles of Association shall be subject to the content approved by the market supervision and administration authority. In the event of any discrepancy between the Chinese version and the English version of the Articles of Association, the Chinese version shall prevail.

By order of the Board
Nexchip Semiconductor Corporation
合肥晶合集成电路股份有限公司
Mr. Tsai Kuo-Chih

Executive Director and chairperson of the Board

Hong Kong, September 29, 2026

As at the date of this announcement, the Board comprises: (i) Mr. Tsai Kuo-Chih and Mr. Zhu Caiwei as Executive Directors; (ii) Mr. Lu Qinhang, Ms. Chen Xiaobei, Mr. Guo Zhaozhi and Mr. Qiu Wensheng as Non-executive Directors; and (iii) Prof. An Guangshi, Prof. Lin Zhiting and Mr. Chen Ting as Independent non-executive Directors.